

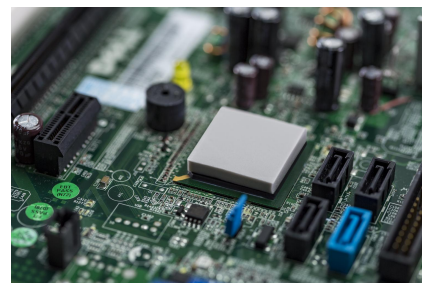
TGP8000HV Thermally Conductive Gap Pad

BENEFITS AND FEATURES

- High thermal performance
- High breakdown voltage
- Excellent surface wetting for low contact resistance
- High reliability
- Electrically insulating

OVERVIEW

Honeywell TGP8000HV is a Thermally Conductive Gap Pad which offers a good combination of low thermal impedance, high breakdown voltage and ease of use across multitude of applications. The naturally tacky property avoids the use of additional adhesive which could inhibit thermal performance. TGP8000HV is available in formats as standard sheets and custom die cut parts in a range of thickness.



TYPICAL APPLICATIONS

- Power devices & modules
- Consumer electronics
- Telecommunications & network servers
- Automotive electronics
- Semiconductors logics & memory

STORAGE & USE

- Shelf Life 12 months at 23±2°C

Property	TGP8000HV	Test Method
Color	Grey	Visual
Thickness (mm)*	0.5-5	ASTM D374
Specific Gravity	3.5	ASTM D792
Hardness (Shore00)	60	ASTM D2240
Thermal Conductivity (W/m·K)	8.0	ASTM D5470
Thermal Impedance (°C·in ² /W)(1mm@10psi) (Typical Value)	0.20	ASTM D5470
Dielectric Strength (V/mm)	8000	ASTM D149
Dielectric Constant@1MHz	8.3	ASTM D150
Volume Resistivity (ohm·cm)	6.47 x 10 ¹⁵	ASTM D257
Flammability Rating	V-0	UL94

* Thickness range: 0.5-5.0mm with 0.25mm incremental
Thickness Tolerance: >=1mm, ±10%
0.5-1mm, ±0.1mm

Honeywell Electronic Materials

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